



YETDA INDUSTRY LTD.

## Technical Data Sheet

MODEL NO : 776RGB4-CA

### Features :

- Package in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

### Applications :

- Indicators
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaN/P/GaAs	Red	Water transparent
InGaN	Green	
InGaN	Blue	

### Electrical/Optical Characteristics(Ta=25°C)

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Spectral half bandwidth	I <sub>F</sub> =20mA	△ λ	R	18		nm
			G	33		
			B	30		
Dominant wavelength	I <sub>F</sub> =20mA	λ D	R	615	620	630
			G	520	525	530
			B	465	470	475
Forward voltage	I <sub>F</sub> =20mA	V <sub>F</sub>	R	1.7	2.0	2.5
			G	2.8	3.1	3.7
			B	2.8	3.1	3.7
Luminous intensity	I <sub>F</sub> =20mA	I <sub>V</sub>	R	125	230	400
			G	520	525	530
			B	80	150	250
Viewing angle at 50% I <sub>V</sub>	I <sub>F</sub> =10mA	2 θ 1/2			120	Deg
Reverse current	V <sub>R</sub> =5V	I <sub>R</sub>			10	μA

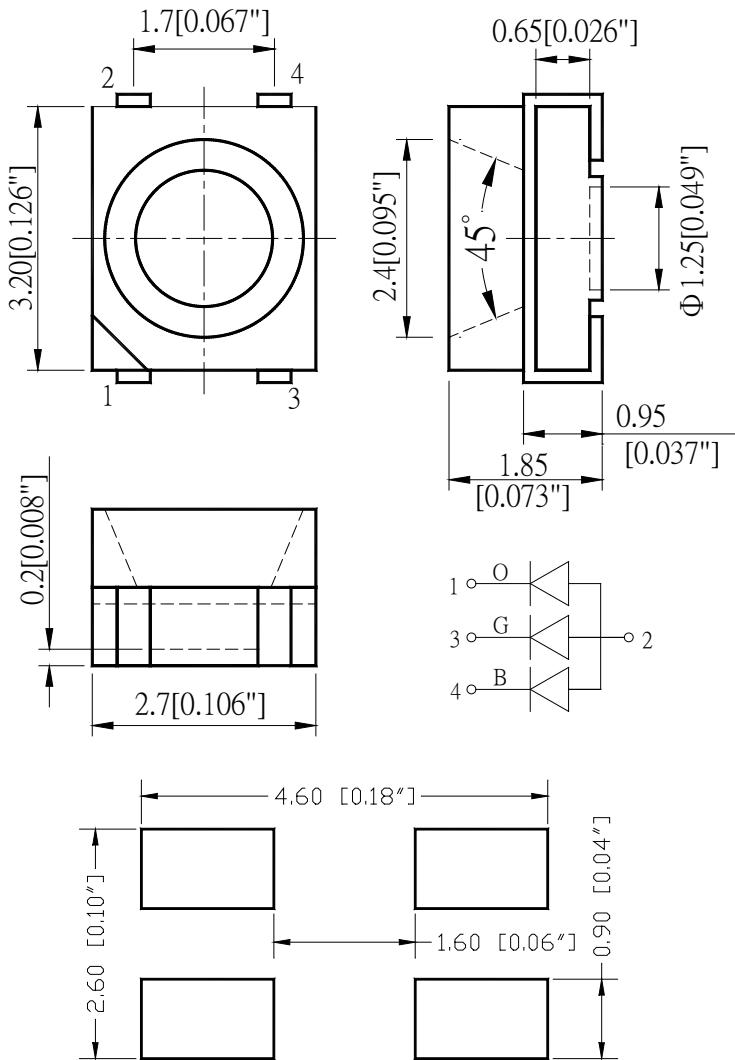


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Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value			Unit
		R	G	B	
Power dissipation	Pd	75	111	111	mW
Forward current	I <sub>F</sub>	30			mA
Reverse voltage	V <sub>R</sub>	5			V
Operating temperature range	T <sub>Op</sub>	-40 ~ +80			°C
Storage temperature range	T <sub>Stg</sub>	-40 ~ +85			°C
Peak pulsing current (1/8 duty f=1kHz)	I <sub>FP</sub>	125			mA

PACKAGING DIMENSIONS (mm):





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## Precautions For Use :

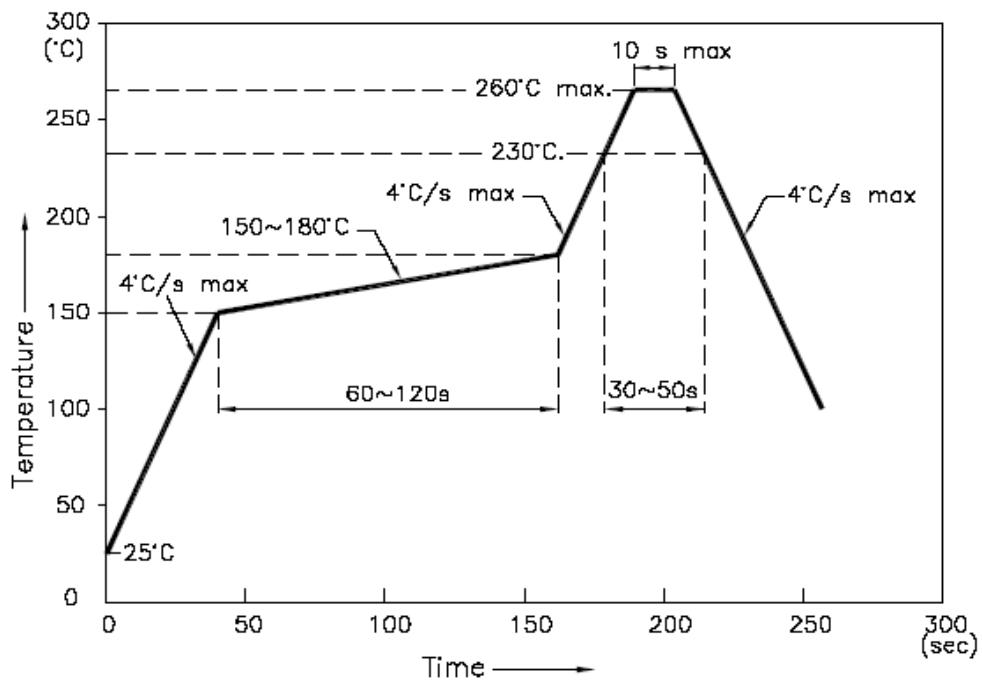
### Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen )

### Storage

1. The operation of temperature and R.H. are :  $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$ , 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent. Considering the tape life, we suggest our customers to use our products within 1.5 year ( from production date ).
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 15hrs.

### ■ Reflow Temp/Time



### NOTES:

1. We recommend the reflow temperature  $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$ . the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.



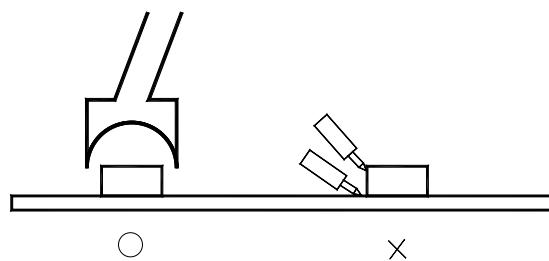
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## ■ Soldering iron

Basic spec is  $\leq 5$ sec when  $260^{\circ}\text{C}$ . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1\text{sec}$ ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under  $230^{\circ}\text{C}$  .

## ■ Rework

1. Customer must finish rework within 5 sec under  $260^{\circ}\text{C}$ .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



## ■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.